OCP
APAC
SUMMIT

TAIPEI CITY

2026 OCP APAC SUMMIT

SPONSOR PROSPECTUS

11–12 August, 2026 | TaiNEX 2 | Taipei City, Taiwan

About the OCP APAC Summit

The OCP APAC Summit is the region's flagship gathering for open data center innovation. Hosted annually in Taipei City, the Summit convenes global hyperscalers, hardware vendors, telecoms, colocation providers, and solution providers to accelerate adoption of OCP-recognized designs. The 2025 edition drew strong attendance and engagement, underscoring the growing importance of APAC within the global OCP Community — and has already generated enthusiasm among organizations preparing to sponsor and participate in 2026.

2025 Program Themes

- AI Clusters
- Chiplets & Advanced Packaging / Photonics
- Cooling Environments
- Networking
- Optical Communication Networks
- Rack & Power
- Server
- Storage
- Future Technologies Symposium (FTS)

A diverse community of hyperscalers, vendors, operators, and academics gather in an open, collaborative environment to advance shared innovation and sustainable infrastructure.

Regional Importance

The APAC region is one of the fastest-growing markets for hyperscale and enterprise data centers. Companies such as AMD, ASE, Broadcom, Google, Meta, Seagate, Supermicro, and TSMC have all contributed to OCP initiatives in the region. Co-hosted in 2025 by the Asia IoT Alliance (AITA) and the Computing Industry Association of Taiwan (CIAT), the APAC Summit demonstrates OCP's strong partnership with regional ecosystems to drive global adoption of open infrastructure.

Community Impact

- The 2025 Summit drew more than 1,500 attendees in Taipei City.
- Over 100 breakout sessions and 20+ deep-dive presentations explored the future of open hardware.
- More than 1,700 workshop registrations underscored strong interest in AI and data center design.
- APAC accounted for 36% of OCP-recognized equipment shipments in 2025 — a key growth driver for the global community.

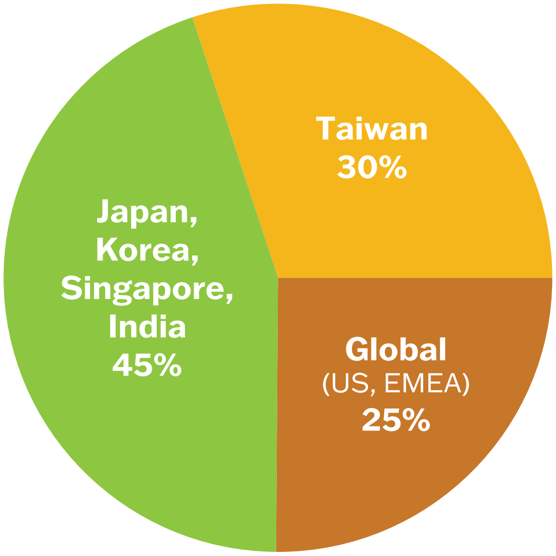
Organization Profile

- Academia
- Colocation Providers
- Enterprise IT
- Hardware Manufacturers
- Hyperscalers
- Research
- Startups
- Telecoms

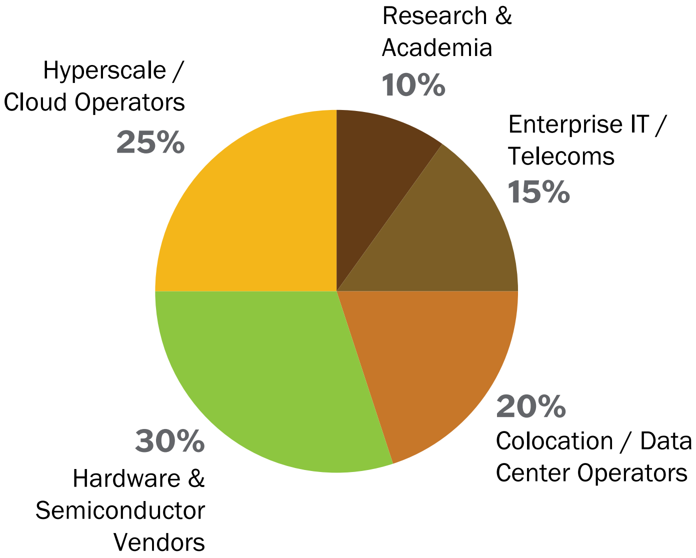
OCP APAC 2025 by the Numbers

The OCP APAC Summit reflects the strength of a global community committed to openness, efficiency, and collaboration. These numbers illustrate the diversity of participants, the breadth of content, and the growing influence of APAC in the adoption of OCP solutions.

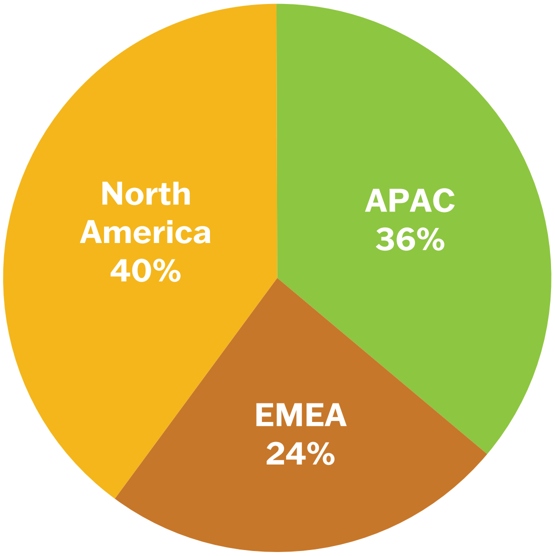
Attendees by Region



Attendees by Organization Type



OCP Recognized Equipment Shipments (2025 Global Share)



2025 Summit Stats

>1,500 Summit Attendees

200+ Speakers

465 Companies Represented

100+ Breakout Sessions

45 Sponsors/ Booths

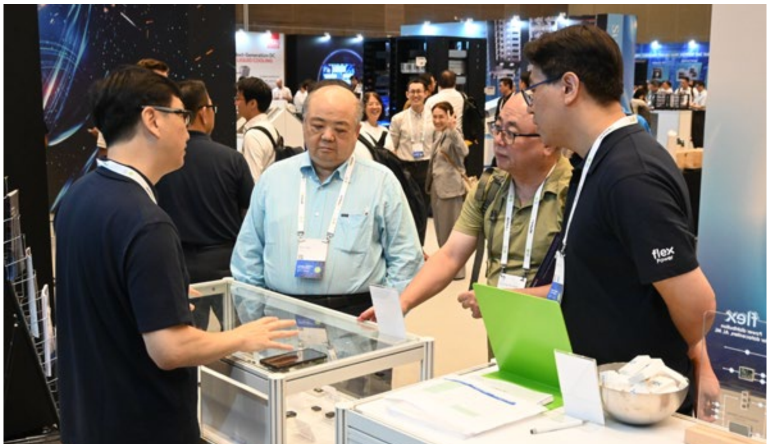
Data based on 2025 OCP APAC Summit highlights; final 2026 attendee demographics will be published after the event.

OCP APAC 2025 Sponsors

The following organizations supported the 2025 OCP APAC Summit through sponsorships and partnerships, reflecting the collaborative spirit of the OCP community.

Previous Sponsors

- ADATA
- AMD
- AMI
- ASE
- ASPEED
- Auras
- Axiado
- BellWether
- BizLink
- Broadcom
- CEJN
- Celestica
- CoolIT Systems
- Danfoss
- Delta
- DigiTimes
- Edgecore Networks
- FADU
- Flex
- Giga Computing
- GIS Group
- Google
- Insyde
- IP infusion
- ITRI (Industrial Technology Research Institute)
- Keysight
- LOTES
- Meta
- Mitac
- MSI
- Murata
- Nuvoton
- Pegatron
- Rittal
- SanBlaze
- Seagate
- STULZ
- Submer
- Supermicro
- TE Connectivity
- Y.S. Tech



2025 Organizations Represented

3m
9elements Gmbh

A

Aboda
ACBEL POLYTECH INC
ACCESS
Accl
Accton
Acebattery
ACHI Capital
Acme
Acon Optics Communications Inc.
Actapio
ADATA
ADI
Admi.
Advanced Energy
Advancing Business Tech-Strategy Division
Advantech
AEI
Aeis
AEWIN
AHSI
Aivres
Ajou University
Akasa Asia Corp
Aletheia
Alfa Laval
Algood Caster Innovations
Alieon
ALLEGRO MICROSYSTEMS
Allianzgi
Allion Labs, Inc.
Alltek Group
Alpha International Development Corp.
Alpha Networks
AMD
American Megatrends Inc (AMI)
Americase
Ampere Computing
Amphenol
Analog Devices
Anord Mardix Asia Pte Ltd
Ansys
Anue
Aopt
Applied Materials
Apresia Systems
Argosy Research
Arm
Arrcus
Artilux
ASE
Asia Vital
Askey
ASPEED Technology
aspencore EE TIMES
ASRock Rack
Astera Labs
Astron Connectivity
ASUS Cloud
Atech
ATMD(Hong Kong) Ltd.
Auo Corporation
AURAS Technology
AVC
Avnet
Axiado

B

B Global Tech
Bac
Beehe Electric Co., Ltd.
Bellwether Electronic Corp.
Best Epitaxy Manufacturing Company Ltd.
BeyondEdge Networks
Beyondsoft
BIN CHUAN Enterprise
Bitmedia Inc.
BizLink
Blackrock
Bowergroupasia
bp
Broadcom
Browave Corporation
Business Today

C

C-tech United Corp.
Cadence
Calnex Solutions
Castrol
Cathay Life Insurance
Cathay Site
ce-link
CEJN
Celestica
Chain Reaction
Chenbro Micom
Chi Chen Technology Co.,ltd.
Chicony Power
CHIEF LAND Electronics Co., Ltd.
China Trust Securities Investment Consulting
Chuan Hong Limited
Chung-ang University
Chunghwa Telecom
CIG
Cisco
Cite
Citigroup
Cloud Security Business Groupng Division
CloudAlpha Capital
CLSA
Colder Product Company (CPC)
Commonwealth Magazine
Compal
Compeq
Concord
Cool Filtration
CoolerMaster
CoolIT Systems
CoolView
Counterpoint Research
Cq Publishing Co.,ltd.
Crealien Co., Ltd
Critical Risk Solution
Ctbc Financial Holding
CTC
Cybergrid Taiwan
Cyient Semiconductor

D

D-REX
Daikin Industries, Ltd.
Daily Cash Inc
Danfoss
Dawnhoof Electrical
DDN
DEKRA iST Reliability Services Inc
Dell
Delta Electronics
Denso Corporation
DiCon Fiberoptics, Inc.
DIGITIMES
Dingzing
Dong Yang High Pressure Industry., Inc
Dorado Software
Dupont

E

EA ELEKTRO-AUTOMATIK
Ea-hwa Enterprise Industrial Co., Ltd.
Eagletek Corp.
East Tender Optoelectronics Corp.(eoc)
Eaton D-IT USA
EBARA CORPORATION
EBMPAPST
Edgecore Networks
EDN Capital
ENEOS Corporation
Engineering HQ
Eqt Private Capital Asia
Equinix
Eraogilvy
Ergon Oil (Singapore) Pte Ltd
Ergon, Inc.
Eugene
Evonik Taiwan
EXFO
Extraordinary News
ExxonMobil Japan

F

F-tek
Factem Co.,ltd.
FADU
Fast SiC Semiconductor Inc.
FCI TAIWAN LIMITED
Fh Trust
Flex
Flextronics International Sweden AB
Flotrend
Formerica OptoElectronics Inc.
Foxconn Interconnect Technology
Foxconn/Ingrasys
Fsas Technologies
Fubon Asset Management
Fubon Life Insurance
Fuh Hwa Securities Investment Trust
FUJIFILM
FuriosaAI
Furukawa Electric Co., Ltd
Furuno Electric Co., Ltd.

G

Gaam
Georg Fischer
Georgia Institute Of Technology
Giga Computing Technology
Gigabyte
Gigacapital
Global Standard Technology
Goodwill Instrument
Google
GPE
Grand Alliance Asset Management
Graphcore
Great Lighting Technologies Inc.
GreatWall Power
Gredmann Group
GreenPower Engineering Corporation
Guangzhou Zhongshan New Materials
Guidance Tamil Nadu
Guoshuo Technology

H

HARTING
Hetone Enterprise Corp. Ltd.
Hewlett Packard Enterprise
Hg Capital
Hitachi high-tech Taiwan
Honhai
Horizon Capital
Hoxin Precision Co.,ltd.
HSBC Securities
Huawei
Hyperscalers

I

IDC
IDEATE INFORMATICS LLP
Idemitsu Kosan Co.,Ltd.
ifm electronic ltd
IIP
ITRI Industrial Technology Research Institute
Infineon
Infinitix
Innolight
InPsytech
Institute For Information Industry
Insyde Software
Intel
Inventec
IOActive
IP Infusion
iPronics
Isaiah Research
ITOCHU Techno-Solutions Corporation

J

J.P.Morgan
J&J Investment
Jabil
JGC Holdings Corporation
Jiansu Greencomputing Tehnology
JPC connectivity

K

Kakaoenterprise
Kaori Heat Treatment Co. Ltd.
KDDI CORPORATION
Keysight Technologies
KGI Securities
King Yuan ELECTRONICS
Korea Institute Of Machinery And Materials
Korea Packaging Integration Association

L

Lam Research
Landmark Optoelectronics Corporation
Lattice Semiconductor
Leadertech
Lemtech Energy Solutions Corporation
Lenovo
Lessengers
LightCounting

2025 Organizations Represented

Lintes Technology
Lite-On technology
Longwell Company
LOTES
Luxshare Tech
LY iTECH
Lynk+

M

Macnica Galaxy Inc.
Macquarie
Magical Galaxy
Manzai
Mashdigi
Mashdigi.com
MC DIGITAL REALTY
MediaTek
Megaunion
Megmeet
Mercuries Life Insurance
Meta
Metanoia Communications., Inc.
Micro-Star International Co., Ltd.
Microchip
Microloops
Microsoft
Millennium
Minebea Mitsumi CO
Minebea Technologies Taiwan Co.,ltd.
Minebeamitsumi Taiwan Branch
Mirror Daily
MiTAC Computing Technology
Mits Component & System Corp.
Mizuho Securities
Molex
Montage Technology
Morgan Stanley
Motul
MPS
MSI
Mufg Bank Ltd
Murata
Musashi Energy Solutions
Musashi Seimitsu Industry

N

Nano And Advanced Material Research Institute
National Institute Of Advanced Industrial Science And Technology
National Taiwan University
National University of Singapore
National Yang Ming Chiao Tung University
Netadmin
Neuberger Berman
Neurair
Neuron Techno Solutions
Nikkei Asia
Nomura
Novamat Applied Material Co.,ltd
Novatek
NTT
NTT Devices
NTT Facilities
NTTDATA Group Corporation
Nuvoton Technology
nVent
Nvidia

O

Oiglvy PR
Omron Electronic Components
Open Computing Singapore Pte Ltd
Osaka University

P

Palc Networks Pvt Ltd
Palo Alto Electron
Panasonic Industry
Panlabs Biologics
Panmnesia
Parker Hannifin
Pascalia Group
Patech Fine Chemicals
pearl chen
Pegatron
Perstorp
Phi Capital
Point2 Technology
Point72
Positronic Asia
Preferred Networks
proteanTecs

Q

Qiaoyue Industrial
Quadrep-TW

R

Rakuten Group, Inc.
Raytek Semiconductor
Readore
Realtek Semiconductor Corp.
Recochem
Renesas
Reuters
Richtek
Rittal
Rivos

S

SAC
Sakura Internet Inc.
Samjintech Co.Ltd.
Samtec
Sanblaze
Saviah Technologies
Schneider Electric
Schroders
Seagate Technology
Semianalysis
Semivision
Senju Electronic (Taiwan) Co.,Ltd
Serialtek
Sharper Business
Shuztung Machinery
Siangsia
SIL-MORE
SIMPLO TECHNOLOGY CO., LTD
Singapore Shangzhaopu Technology
Soitec
Solar Applied Material Technologies
Solidigm
SOLUM
Southco Inc
ST
ST Telemedia Global Data Centre (STTGDC)
Stäubli Electrical Connectors
Stl-techonolgy
Stmicroelectronics
STT Global Data Centres
Studio Bookmark
Stulz
Submer
Sumitomo Electric
SUNON
Sunonwealth
Sunpartner International
SunyaEK Computing
Supermicro
SUPREME ELECTRONIC
Synopsys
Syntacore

T

Taisol Electronics
Taiwan Microloops Corp.
Taiwan Murata Electronics
Taiwan Semiconductor Manufacturing Company, Ltd.
TAIWAN TAIYO YUDEN CO., LTD.
TARNG YU ENTERPRISE
TDK Components
TE Connectivity
Techford
Techinsights
Technology Platforms Division
Tektronix
Teletrx.co
Teng Yue Partners
Teracule
The Chemours Company
The Cid Group
The Grand Valley Foundation
Tianrui Technology
TIQCIT
Tok Taiwan
Topco-scientific
Trande -van Information On Services Co.
Treasure Capital Asia
Trend Power Technology
Trendo
Trinity Thermal Solutions
Trust-tek Corp
TSMC
Turvo International Co., Ltd
Tüv Rheinland Taiwan Ltd.
TYU

U

UBS
UfiSpace
UL Solutions
Ulink Technology
Unimicron
Unist
Usi

V

Verdigiris
Vertiv
Vianext
Vicor
Vitalcore Technology Ltd.
VTC

W

W. Investment Co. Ltd.
Wealth Magazine
Winstek Semiconductor Co.
Wistron Corporation
Wiwynn
WNC Corporation
Wolley Inc.
Wonder Advanced Materials Co., Ltd.
Wt Microelectronics
wtmec

X

XFusion International
Xing Mobility

Y

Yen Sun Technology Corp.
Yggdrasil Capital
Yu Ru Chen
Yuanshan Technology
Yuding Technology Co.,ltd.
YUGA AI Company Limited

Z

ZELOS
Zhaopu Technology
Zhongyang Optoelectronics
ZONTA
ZT Systems
ZutaCore

Schedule Overview

The 2026 OCP APAC Summit will bring together keynotes, breakout sessions, expo hall and networking opportunities across two days. The sample agenda highlights the program structure; final session details and speakers will be announced as the event approaches.

Day 1: Tuesday, 11 August 2026*

Time	Event
Morning	Registration
Late Morning	Keynotes
Lunch	Lunch Break
Afternoon	Exhibit Hall Opens
Afternoon	Breakout Sessions
Evening	Welcome Reception

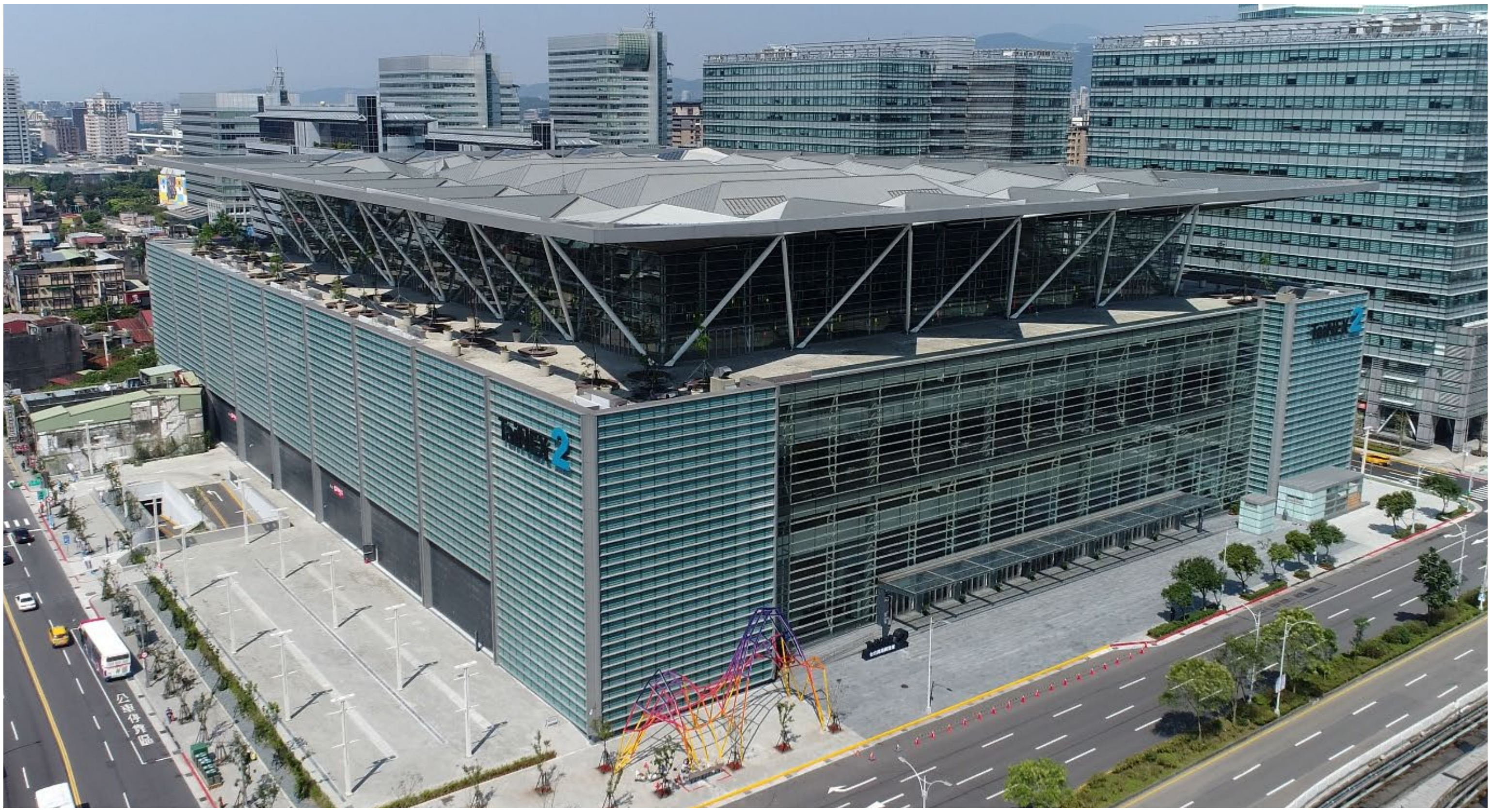
Day 2: Wednesday, 12 August 2026*

Time	Event
Morning	Breakout Sessions
Lunch	Lunch Break
Afternoon	Breakout Sessions
All Day	Exhibit Hall Open

**Schedule is subject to change.*

Venue

Taipei Nangang Exhibition Center, Hall 2 (TaiNEX 2)
No. 2, Jingmao 2nd Rd, Nangang District, Taipei City, Taiwan



台北南港展覽館2館
TAIPEI NANGANG EXHIBITION CENTER, HALL 2

Booth Sponsorship

Showcase your company's innovations at the heart of the 2026 OCP APAC Summit. Our booth sponsorship packages offer turnkey exhibits, brand visibility, and access to key decision-makers, with flexible options to match your organization's goals.

Package	**Elite***	**Premier***	**Plus***	**Startup**
Price	$45,000	$30,000	$15,000	$5,000
Booth Size	9m x 6m	6m x 3m	3m x 3m	3m x 3m
Complimentary Passes	15	10	7	3
Availability	5 Available	15 Available	25 Available	5 Available
Turnkey Booth Inclusions	• Custom Printed Back Wall (Logo or Artwork) LED • Monitor with Stand (Elite and Premier only) • Lead Retrieval Device (excludes Startup) • Wi-Fi Access • 110v/20A Electricity + Power Strip Locking • Counter • Choice of Carpet Color • Chairs • Waste Bin			

**OCP Tiered Membership discounts available and apply to booths only.*

Event Sponsorship

Make your brand part of the Summit experience. Event sponsorships provide prominent visibility in high-traffic areas and at networking gatherings, giving sponsors lasting exposure with attendees throughout the 2026 OCP APAC Summit.

Sponsorship Item	Price	Availability	Notes	Passes Included
Welcome Reception	$15,000	1 Available	Day 1 Evening: Logo on reception signage and OCP website	4
Community Lounge	$15,000	1 Available	Dedicated lounge area with signage and 1 monitor showcasing your custom content (no audio)	4
Power Up Lounge	$15,000	1 Available	Dedicated lounge area with signage and charging stations.	4
Lanyards	$15,000	1 Available	Logo prominently featured on attendee lanyards	4
Tote Bags	$15,000	1 Available	Logo prominently featured on Summit bags	4
Coffee – Both Days	$15,000	1 Available	Logo prominently featured in conjunction with coffee service	4
Water – Both Days	$15,000	1 Available	Logo prominently featured on water stations throughout venue	4
Lunch – Both Days	$15,000	1 Available	Logo prominently featured on signage during lunch service	4
Site Tours	$10,000	3 Available	OCP will arrange communications to your desired attendees	2
Future Technologies Symposium (FTS)	$15,000	1 Available	Logo prominently featured on signage and 5 minutes to address audience during the Symposium	4
Tote Bag Inserts	$10,000	3 Available	Branded collateral or promotional items included in tote bags	2
Private Meeting Room	$2,500	6 Available	Access to a private meeting room for up to 8 people - space and furniture based on venue. (Available to Booth Sponsors Only)	N/A

2026 OCP APAC Summit – Sponsorship Contract

Event Dates: August 11–12, 2026 **Venue:** Tainex 2, Taipei City, Taiwan

This Agreement is made and entered into as of [date] ___________ between the Open Compute Project (“OCP”) Foundation and:

Name of Organization (*how it should be displayed on OCP site*): ________________________________

Address: ____

City: ________________ State/Province/Region: ________________ Zip/Postal Code: __________

Country: ______________________ Phone: ______________________________

Sponsorship Logistics Contact Name: ___________________ Email: ________________________

URL you want linked to your logo: ______________________________________

___ This is a co-sponsorship (max 1 additional logo) Co-sponsor Name: ____________________

Sponsor Options for the 2026 OCP APAC Summit (the “Event”)		
Booth Sponsorships		
___ Elite: $45,000 (9m x 6m booth)	___ Premier: $30,000 (6m x 3m booth)	___ Plus: $15,000 (3m x 3m booth)
___ Meeting Room: $ 2,500		
Event Sponsorships (Member discounts do not apply)		
___ Welcome Reception: $15,000	___ Coffee (Both Days): $15,000	___ Tote Bags: $15,000
___ Community Lounge: $15,000	___ Lunch (Both Days): $15,000	___ Tote Bag Insert: $10,000
___ Power Up Lounge: $15,000	___ Water Sponsor (Both Days): $15,000	___ Site Tour: $10,000
___ Lanyards: $15,000		___ FTS Sponsor: $10,000

* ***All prices listed in USD. Final invoice may reflect VAT charge in addition to sponsorship total below, if organization does not have an entity located in Taiwan. Please contact accounting@opencompute.org for clarifications.***

Tiered Membership Discount

If your company is an OCP Tiered Member, please check the applicable discount below. Must be a Member in good standing at the time of the 2026 APAC Summit. **Membership discounts apply to booths only. Marketing and Event sponsorships, speaking add-ons, and meeting rooms are not eligible for discounts.**

___ Platinum Tiered Member (15%) ___ Gold Tiered Member (10%) ___ Silver Tiered Member (7%)

Total Amount (after discounts if applicable): $ ____________

OCP Contact: Kate Hendle, Manager of Events, kate@opencompute.org

Payment Information: Acceptable forms of payment include ACH, wire transfers, credit cards and checks. If paying by check, please make checks payable to:
GIS Group Global Co., Ltd., No. 382, Shin-yi Road Sec. 4, Taipei 106, Taiwan

Terms & Conditions

1. *Payment must be in United States Dollars. All payments must be made to GIS Group Global Co., Ltd. and provided in cleared funds to the bank account provided on the invoice not later than net 30 days of the date of the invoice. All fees are exclusive of all applicable sales, use, value-added and similar taxes, which Sponsor shall pay in addition to the fees at the rate prevailing on the date of the invoice. Payment must be received prior to the event or the sponsorship will be considered invalid. Account must be current to participate.*

2. *Sponsor speakers are required to submit their presentation content for review by the Open Compute Foundation by the date indicated in the prospectus. Failure to submit your content for review by the foundation can result in the loss of your speaking opportunity.*

3. *Sponsor is responsible for meeting all deadlines for delivery of materials and artwork. Past due materials may be excluded from the conference program, signage, and other opportunities included in the sponsor's contribution level.*

4. *Sponsor is responsible for any shipping and receiving costs the venue may charge for materials shipped directly to the venue.*

5. *Exhibit Locations. Booth/table location assignments will be selected by the sponsor company on a first-signed, first-served basis, and may be modified by the Foundation due to changes in event layout, venue or other factors.*

6. *Restrictions in Operations of Exhibits. The OCP Foundation and its representatives reserve the right to restrict or remove exhibits which, because of noise, method of operation, materials, or for any other reason, may become objectionable to the reasonable attendee or the venue. In the event of such restriction or eviction, the OCP Foundation is not liable for any refunds, rentals, or other exhibit expenses incurred by the Sponsor.*

7. *Care of Building. The Sponsor shall not injure or deface the walls, floors, tables, or equipment of the building. The Sponsor assumes all liability for any damage incurred.*

8. *Catastrophe. In the event that because of war, fire, strike, government regulation, natural disaster, pandemic, public catastrophe, act of God, or other cause, the conference or any part thereof is prevented from being held, or is canceled by the OCP Foundation, the OCP Foundation shall determine any refund to a Sponsor after deducting any expenses incurred by the OCP Foundation but in no case shall the amount of the refund to the Sponsor exceed the amount of the fee paid.*

9. *Cancellations made by the Sponsor 6 months or more prior to the event will not be subject to any fee. Cancellations made between 3 and 6 months prior to the event are liable for 50% of the sponsorship fee or the cost of equivalent services/equipment if the sponsorship is an in-kind or barter arrangement. Cancellations made less than 3 months prior to the event are liable for the entire sponsorship fee or the cost of equivalent services/equipment. All cancellations must be made in writing to the OCP Foundation.*

10. *Trademarks. Each party retains all rights and ownership to its own trademarks and must obtain prior approval from the other party for any use of the other party's names or marks for the purpose of marketing, advertising and otherwise promoting participation in and/or sponsorship of (as described in this Agreement) the Event, which approval shall not be unreasonably withheld or delayed. Sponsor shall provide to OCP Foundation any artwork necessary for use of Sponsor's marks, name or logo. Sponsor agrees to abide by, and be bound by, the Open Compute Project Trademark Usage Guidelines, which are available at https://bit.ly/2QwPmUN, including as this may be updated by OCP Foundation from time to time. At the request of OCP Foundation, Sponsor will provide samples of its uses of OCP Foundation marks.*

11. *OCP Materials Release. If I am presenting at the OCP APAC Summit, I acknowledge that my Presentation and any ancillary materials I provide to OCP in connection with my Presentation, including without limitation any white paper, article, photograph, likeness, or professional biography (together, "Materials") are made available under the Creative Commons Attribution-ShareAlike 4.0 International License found at https://creativecommons.org/licenses/by-sa/4.0/, or any later version, and without limiting the foregoing, OCP may make the Materials available under such terms. OCP may exercise its rights hereunder in all forms and media, whether now known or hereafter developed, throughout the world in perpetuity, royalty-free. My authorization and acknowledgement above are irrevocable and extends to OCP and its agents, successors, and assigns. I hereby waive any right to inspect or approve the Recordings. I acknowledge that OCP is under no obligation to use the Recordings, or Materials if applicable, in any manner. I hereby represent that I have the authority to grant the rights and licenses herein. And if I am presenting at an OCP event, I further represent and warrant that the Materials do not and will not violate the rights of any third party, including without limitation rights in intellectual property. I also represent that, to the extent the Materials include materials owned or created by any third-party, I have obtained permission for its use consistent with the foregoing. I will provide OCP evidence of such permission upon OCP's request.*

12. *Miscellaneous. This Agreement shall be governed by the internal laws of the State of Delaware without regard to principles of conflicts of laws. Any disputes shall be heard exclusively in the state or federal courts located in Delaware, and both parties consent to the jurisdiction of such courts. Sponsor cannot assign any rights under this Agreement without the prior written consent of the OCP Foundation; any unauthorized assignment is null and void. This is the entire agreement of the parties and cannot be amended or changed except in a writing signed by both parties.*

13. *GDPR Policy. OCP will treat all information you provide in accordance with the OCP Privacy Policy posted at http://www.opencompute.org/privacy/. This includes cookies and any other information we may collect. By signing this contract, you acknowledge and accept OCP's Privacy Policy and give your consent to the transfer of your personal information to the United States, which may have less protection than your jurisdiction of residence.*

14. *BADGE SWAPPING: Badge swapping and/or trading is strictly prohibited at OCP events. Attendees must wear their badge at all times on the event premises. Any attendee caught without a badge will be escorted to registration to show an ID and charged a reprint fee if the badge cannot be found. If caught wearing another attendee's badge or leaving the premises with multiple badges with the intent to distribute to other attendees, all badges will be confiscated, and this person may be removed from the event. OCP keeps historical records of companies and sponsors who are regular offenders of badge swapping. OCP reserves the right to deny attendance, sponsorship, and speaking opportunities to any individuals or organizations that do not abide by OCP event regulations.*

In witness whereof, the parties have caused this Agreement to be executed by their duly authorized representatives.

Sponsor:

Signature: ______________________________

Printed Name: ___________________________

Title: ______________________________

Date: ______________________

Open Compute Project Foundation:

Signature: ______________________________

Printed Name: ___________________________

Title: ______________________________

Date: ______________________

Sponsorship deadline is Friday, May 1, 2026. Sponsorships & booth locations are awarded in the order that they are received.